

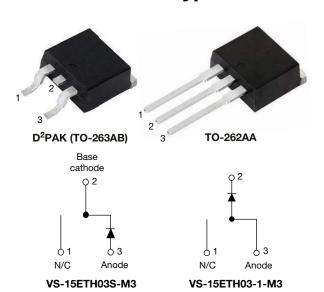
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Vishay Semiconductors

HALOGEN

FREE

# Hyperfast Rectifier, 15 A FRED Pt®



PRIMARY CHARACTERISTICS								
I <sub>F(AV)</sub> 15 A								
$V_{R}$	300 V							
V <sub>F</sub> at I <sub>F</sub>	0.85 V							
t <sub>rr</sub> (typ.)	40 ns							
T <sub>J</sub> max.	175 °C							
Package	D <sup>2</sup> PAK (TO-263AB), TO-262AA							
Circuit configuration	Single							

#### **FEATURES**

- · Hyperfast recovery time
- Low forward voltage drop
- · Low leakage current
- 175 °C operating junction temperature
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

### **DESCRIPTION / APPLICATIONS**

Vishay Semiconductors 300 V series are the state of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop and hyperfast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS				
Repetitive peak reverse voltage	$V_{RRM}$		300	V				
Average rectified forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 142 °C	15	۸				
Non-repetitive peak surge current	I <sub>FSM</sub>	T <sub>J</sub> = 25 °C	140	Α				
Operating junction and storage temperatures	T <sub>J</sub> , T <sub>Stg</sub>		-65 to +175	°C				

<b>ELECTRICAL SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS			
Breakdown voltage, blocking voltage	V <sub>BR</sub> , V <sub>R</sub>	Ι <sub>R</sub> = 100 μΑ	300	-	-	.,			
Forward voltage	V <sub>F</sub>	I <sub>F</sub> = 15 A	-	1.05	1.25	V			
Torward vortage	VF.	I <sub>F</sub> = 15 A, T <sub>J</sub> = 125 °C	-	0.85	1.00				
Reverse leakage current	ı	$V_R = V_R$ rated	-	0.05	40				
neverse leakage current	I <sub>R</sub>	$T_J = 125$ °C, $V_R = V_R$ rated	-	12	400	μA			
Junction capacitance	C <sub>T</sub>	V <sub>R</sub> = 300 V	-	45	-	pF			
Series inductance	L <sub>S</sub>	Measured lead to lead 5 mm from package body	-	8	-	nΗ			



<b>DYNAMIC RECOVERY CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS	
		$I_F = 1.0 \text{ A}, dI_F/dt =$	50 A/μs, V <sub>R</sub> = 30 V	-	-	40		
Reverse recovery time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C		-	32	-	ns - A	
		T <sub>J</sub> = 125 °C	]	-	45	-		
Peak recovery current	I <sub>RRM</sub>	T <sub>J</sub> = 25 °C	I <sub>F</sub> = 15 A   dI <sub>F</sub> /dt = -200 A/μs ·   V <sub>B</sub> = 200 V	-	2.4	-		
		T <sub>J</sub> = 125 °C		=	6.1	-		
Davis and the same	Q <sub>rr</sub>	T <sub>J</sub> = 25 °C	] "	=	38	-	nC	
Reverse recovery charge		T <sub>J</sub> = 125 °C	]	-	137	=		

THERMAL - MECHANICAL SPECIFICATIONS									
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-65	-	175	°C			
Thermal resistance, junction to case per leg	R <sub>thJC</sub>		-	1.02	2.0				
Thermal resistance, junction to ambient per leg	R <sub>thJA</sub>	Typical socket mount	-	-	70	°C/W			
Thermal resistance, case to heatsink	R <sub>thCS</sub>	R <sub>thCS</sub> Mounting surface, flat, smooth, and greased		0.2	-				
Weight			-	2.0	-	g			
weight			-	0.07	-	oz.			
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)			
Mandings device		Case style D <sup>2</sup> PAK (TO-263AB) 15ETH03S			H03S				
Marking device		Case style TO-262AA		15ETH03-1					

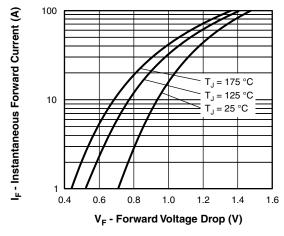


Fig. 1 - Typical Forward Voltage Drop Characteristics

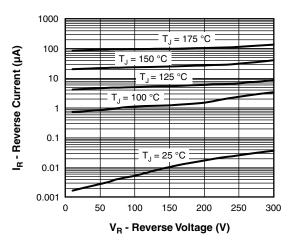


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

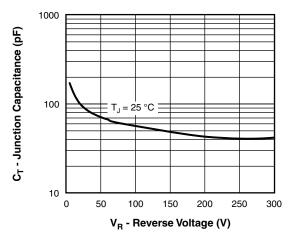


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

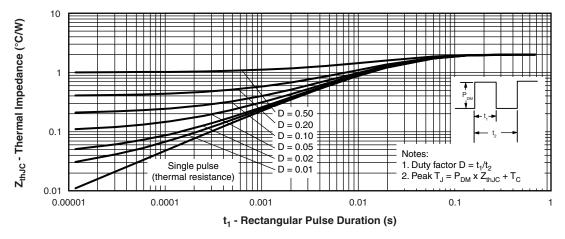


Fig. 4 - Maximum Thermal Impedance Z<sub>thJC</sub> Characteristics

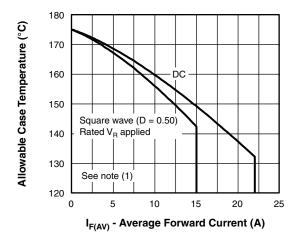


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

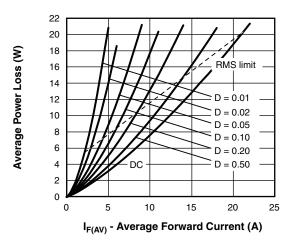


Fig. 6 - Forward Power Loss Characteristics

# VS-15ETH03S-M3, VS-15ETH03-1-M3

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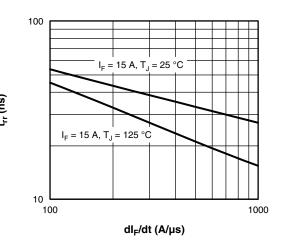


Fig. 7 - Typical Reverse Recovery Time vs. dl<sub>F</sub>/dt

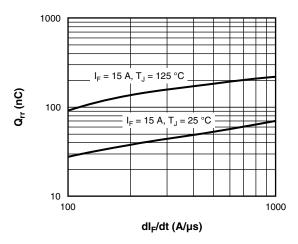
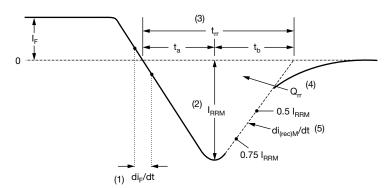


Fig. 8 - Typical Stored Charge vs. dl<sub>F</sub>/dt

#### Note

 $\begin{array}{ll} \text{(1)} & \text{Formula used: } T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}; \\ Pd = \text{forward power loss} = I_{F(AV)} \times V_{FM} \text{ at } (I_{F(AV)}/D) \text{ (see fig. 6)}; \\ Pd_{REV} = \text{inverse power loss} = V_{R1} \times I_R \text{ (1 - D); } I_R \text{ at } V_{R1} = \text{rated } V_R \\ \end{array}$ 



- (1) di<sub>F</sub>/dt rate of change of current through zero crossing
- (2)  $I_{RRM}$  peak reverse recovery current
- (3) t<sub>rr</sub> reverse recovery time measured from zero crossing point of negative going I<sub>F</sub> to point where a line passing through 0.75 I<sub>RRM</sub> and 0.50 I<sub>RRM</sub> extrapolated to zero current.
- (4)  $\mathbf{Q}_{rr}$  area under curve defined by  $\mathbf{t}_{rr}$  and  $\mathbf{I}_{\text{RRM}}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

(5) di<sub>(rec)M</sub>/dt - peak rate of change of current during t<sub>b</sub> portion of t<sub>rr</sub>

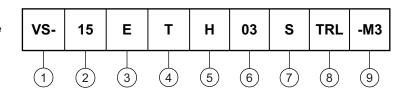
Fig. 9 - Reverse Recovery Waveform and Definitions

# VS-15ETH03S-M3, VS-15ETH03-1-M3

### Vishay Semiconductors

### **ORDERING INFORMATION TABLE**

Device code



Vishay Semiconductors product

2 - Current rating (15 A)

3 - E = single

4 - T = TO-220, D<sup>2</sup>PAK (TO-263AB)

5 - H = hyperfast rectifier

6 - Voltage rating (03 = 300 V)

7 - • S =  $D^2PAK$  (TO-263AB)

• -1 = TO-262AA

• None = tube (50 pieces)

• TRL = tape and reel (left oriented, for D<sup>2</sup>PAK (TO-263AB) package)

• TRR = tape and reel (right oriented, for D<sup>2</sup>PAK (TO-263AB) package)

9 - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

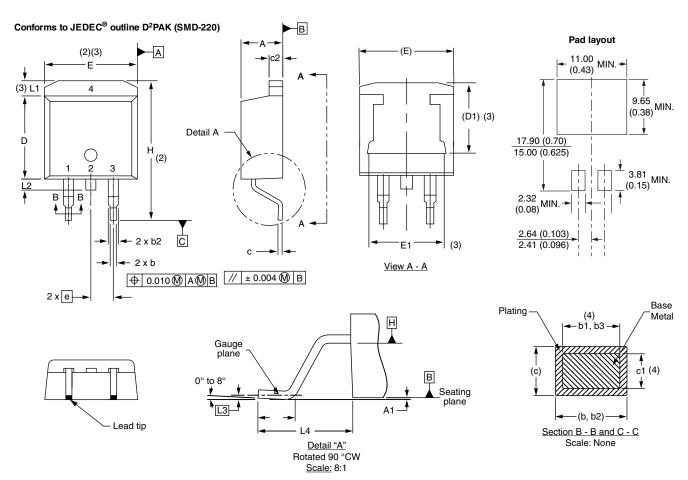
ORDERING INFORMATION (Example)								
PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION								
VS-15ETH03S-M3	50	Antistatic plastic tubes						
VS-15ETH03STRL-M3	800	13" diameter plastic tape and reel						
VS-15ETH03STRR-M3	800	13" diameter plastic tape and reel						
VS-15ETH03-1-M3	50	Antistatic plastic tubes						

LINKS TO RELATED DOCUMEN	NTS	
Dimensions	D <sup>2</sup> PAK (TO-263AB)	www.vishay.com/doc?96164
Differisions	TO-262AA	www.vishay.com/doc?96165
Part marking information	D <sup>2</sup> PAK (TO-263AB)	www.vishay.com/doc?95444
Fart marking information	TO-262AA	www.vishay.com/doc?95443
Packaging information		www.vishay.com/doc?96424
SPICE model		www.vishay.com/doc?96567



## D<sup>2</sup>PAK

### **DIMENSIONS** in millimeters and inches



SYMBOL	MILLIM	ETERS	INC	HES	NOTES	TES SYMBOL -		MILLIM	ETERS	INC	HES	NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	NOTES	STWIDOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.06	4.83	0.160	0.190			D1	6.86	8.00	0.270	0.315	3
A1	0.00	0.254	0.000	0.010			E	9.65	10.67	0.380	0.420	2, 3
b	0.51	0.99	0.020	0.039			E1	7.90	8.80	0.311	0.346	3
b1	0.51	0.89	0.020	0.035	4		е	2.54	BSC	0.100	BSC	
b2	1.14	1.78	0.045	0.070			Н	14.61	15.88	0.575	0.625	
b3	1.14	1.73	0.045	0.068	4		L	1.78	2.79	0.070	0.110	
С	0.38	0.74	0.015	0.029			L1	-	1.65	-	0.066	3
c1	0.38	0.58	0.015	0.023	4		L2	1.27	1.78	0.050	0.070	
c2	1.14	1.65	0.045	0.065			L3	0.25	BSC	0.010	BSC	
D	8.51	9.65	0.335	0.380	2		L4	4.78	5.28	0.188	0.208	

#### Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inches
- (7) Outline conforms to JEDEC® outline TO-263AB

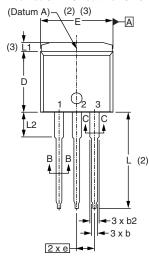
Revision: 13-Jul-17 Document Number: 96164

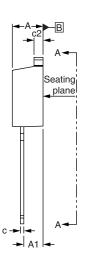


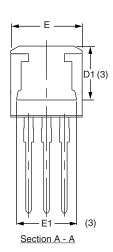
### **TO-262AA**

### **DIMENSIONS** in millimeters and inches

#### Modified JEDEC® outline TO-262







**⊕** 0.010 **M** A**M** B

#### Lead assignments

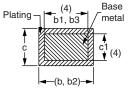


**Diodes** 

1. - Anode (two die)/open (one die)

2., 4. - Cathode

3. - Anode



Section B - B and C - C Scale: None

SYMBOL	MILLIN	IETERS	INC	INCHES			
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES		
А	4.06	4.83	0.160	0.190			
A1	2.03	3.02	0.080	0.119			
b	0.51	0.99	0.020	0.039			
b1	0.51	0.89	0.020	0.035	4		
b2	1.14	1.78	0.045	0.070			
b3	1.14	1.73	0.045	0.068	4		
С	0.38	0.74	0.015	0.029			
c1	0.38	0.58	0.015	0.023	4		
c2	1.14	1.65	0.045	0.065			
D	8.51	9.65	0.335	0.380	2		
D1	6.86	8.00	0.270	0.315	3		
E	9.65	10.67	0.380	0.420	2, 3		
E1	7.90	8.80	0.311	0.346	3		
е	2.54 BSC		0.100	BSC			
L	13.46	14.10	0.530	0.555			
L1	-	1.65	-	0.065	3		
L2	3.56	3.71	0.140	0.146			

#### **Notes**

(4) Dimension b1 and c1 apply to base metal only

Controlling dimension: inches

<sup>(1)</sup> Dimensioning and tolerancing as per ASME Y14.5M-1994
(2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body

Thermal pad contour optional within dimension E, L1, D1 and E1

Outline conform to JEDEC® TO-262 except A1 (max.), b (min., max.), b1 (min.), b2 (max.), c (min.), c1(min.), c2 (max.), D (min.), E (max.), L1 (max.), L2 (min., max.)



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